

ABSTRACT

There is provided a structure for connecting substrates to each other, which is capable of thinning an electronic device on which a plurality of circuit boards is mounted, saving a space of the electronic device, and detaching a circuit board from the electronic device. The circuit board unit includes a first substrate 1 including, on a surface thereof, a first group of electrode terminals 10 arranged in a matrix, a second substrate 2 including, on a surface thereof, a second group of electrode terminals 20 arranged in a matrix in alignment with the first group of electrode terminals 10, and an anisotropic electrical conductor 3 sandwiched between the first and second substrates 10, 20. The first and second substrates 1, 2 and the anisotropic electrical conductor 3 are pressurized by means of a pressurizer 4 to electrically connect the electrode terminals 10 and 20 to each other through the anisotropic electrical conductor 3.